



Appl. No. :  unknown
Filed :  Herewith

OS removing the wafer support from the thermal treatment chamber after processing
the wafer.

REMARKS

The specific changes to the specification and the amended claims are shown on a separate set of pages attached hereto and entitled VERSION WITH MARKINGS TO SHOW CHANGES MADE, which follows the signature page of this Amendment. On this set of pages, the insertions are underlined while the ~~deletions are struck through~~.

The foregoing amendments are to more closely conform the application to U.S. practice. No new matter is added. Entry of the amendments is respectfully requested.

Respectfully submitted,

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Dated: 11/6/01

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION:

The paragraph beginning on page 1, line 3, has been amended as follows:



The present invention relates to a method ~~according to the preamble of Claim 1 of~~
transferring a wafer between a thermal treatment chamber and a thermal treatment installation.

Background of the Invention

U.S. Patent No. 5,162,047 discloses a thermal treatment installation which comprises a thermal treatment chamber, a "wafer boat"/rings assembly, a loading device and a transport device. With this arrangement the loading device serves to place wafers in and to remove wafers from the assembly and the transport device serves to place the assembly in and remove the assembly from the thermal treatment chamber.

The paragraph on page 3, line 10, has been amended as follows:

~~The aim is achieved with a method as described above having the characterising features of claim 1.~~
An aspect of the present invention involves a method of transferring wafers between a thermal treatment chamber and a thermal treatment installation. The treatment chamber has a top section and a bottom section between which the wafer is accommodated during treatment. The thermal treatment installation has a loading chamber having loading means and transport means. The wafer is place on a wafer support while in the loading chamber, wherein the wafer support is configured as a ring having support elements to support the wafer. The wafer support loaded with the wafer is inserted into the thermal treatment chamber so that the wafer and the wafer support are positioned between the top section and the bottom section. The wafer is individually processed in the thermal treatment chamber. After processing the wafer, the wafer support is removed from the thermal treatment chamber.

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ABSTRACT

Method For Transferring Wafers And Ring

For wafer processing, wafers are transferred between a thermal treatment chamber and a thermal treatment installation. The treatment chamber has a top section and a bottom section between which the wafer is accommodated during treatment. The thermal treatment installation has a loading chamber having loading means and transport means. The wafer is place on a wafer support while in the loading chamber, wherein the wafer support is configured as a ring having support elements to support the wafer. The wafer support loaded with the wafer is inserted into the thermal treatment chamber so that the wafer and the wafer support are positioned between the top section and the bottom section. The wafer is individually processed in the thermal treatment chamber. After processing the wafer, the wafer support is removed from the thermal treatment chamber.

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